

March 2010

# BS170 / MMBF170 N-Channel Enhancement Mode Field Effect Transistor

#### **General Description**

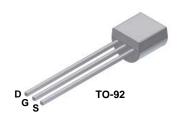
These N-Channel enhancement mode field effect transistors are produced using Fairchild's proprietary, high cell density, DMOS technology. These products have been designed to minimize on-state resistance while provide rugged, reliable, and fast switching performance. They can be used in most applications requiring up to 500mA DC. These products are particularly suited for low voltage, low current applications such as small servo motor control, power MOSFET gate drivers, and other switching applications.

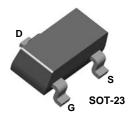
#### **Features**

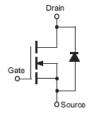
- High density cell design for low R<sub>DS(ON)</sub>.
- Voltage controlled small signal switch.
- Rugged and reliable.
- High saturation current capability.

#### **BS170**

### **MMBF170**







#### **Absolute Maximum Ratings** T<sub>A</sub> = 25°C unless otherwise noted

Symbol	Parameter	BS170	MMBF170	Units
V <sub>DSS</sub>	Drain-Source Voltage		V	
$V_{DGR}$	Drain-Gate Voltage ( $R_{GS} \le 1M\Omega$ )	(	V	
V <sub>GSS</sub>	Gate-Source Voltage	±	V	
I <sub>D</sub>	Drain Current - Continuous	500	500	mA
	- Pulsed	1200	800	- IIIA
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range	- 55	°C	
T <sub>L</sub>	Maximum Lead Temperature for Soldering Purposes, 1/16" from Case for 10 Seconds	3	00	°C

### Thermal Characteristics $T_A = 25$ °C unless otherwise noted

Symbol	Parameter	BS170	MMBF170	Units
P <sub>D</sub>	Maximum Power Dissipation Derate above 25°C	830 6.6	300 2.4	mW mW/°C
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	150	417	°C/W

## $\textbf{Electrical Characteristics} \quad \textbf{T}_{A}\text{=}25^{\circ}\text{C unless otherwise noted}$

Symbol	Parameter	Conditions	Type	Min.	Тур.	Max.	Units
OFF CHA	RACTERISTICS						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 100 \mu A$	All	60			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = 25V, V_{GS} = 0V$	All			0.5	μΑ
I <sub>GSSF</sub>	Gate - Body Leakage, Forward	$V_{GS} = 15V$ , $V_{DS} = 0V$	All			10	nA
ON CHAR	RACTERISTICS (Notes 1)						
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}$ , $I_D = 1mA$	All	8.0	2.1	3	V
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	$V_{GS} = 10V, I_D = 200mA$	All		1.2	5	Ω
9 <sub>FS</sub>	Forward Transconductance	$V_{DS} = 10V, I_{D} = 200 \text{mA}$	BS170		320		mS
		$V_{DS} \ge 2 V_{DS(on)},$ $I_D = 200 \text{mA}$	MMBF170		320		
Dynamic	Characteristics		1				
C <sub>iss</sub>	Input Capacitance	$V_{DS} = 10V, V_{GS} = 0V,$	All		24	40	pF
C <sub>oss</sub>	Output Capacitance	f = 1.0MHz	All		17	30	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		All		7	10	pF
Switching	Characteristics (Notes 1)				•		
t <sub>on</sub>	Turn-On Time	$V_{DD} = 25V, I_{D} = 200mA, V_{GS} = 10V, R_{GEN} = 25\Omega$	BS170			10	ns
		$V_{DD} = 25V, I_{D} = 500mA,$ $V_{GS} = 10V, R_{GEN} = 50\Omega$	MMBF170			10	
t <sub>off</sub>	Turn-Off Time	$V_{DD} = 25V, I_{D} = 200 \text{mA},$ $V_{GS} = 10V, R_{GEN} = 25\Omega$	BS170			10	ns
		$V_{DD} = 25V, I_D = 500 \text{mA},$ $V_{GS} = 10V, R_{GEN} = 50\Omega$	MMBF170			10	

#### Note:

### **Ordering Information**

Part Number	Package	Package Type	Lead Frame	Pin array
BS170	TO-92	BULK	STRAIGHT	DGS
BS170_D26Z	TO-92	Tape and Reel	FORMING	DGS
BS170_D27Z	TO-92	Tape and Reel	FORMING	DGS
BS170_D74Z	TO-92	AMMO	FORMING	DGS
BS170_D75Z	TO-92	AMMO	FORMING	DGS
MMBF170	SOT-23	Tape and Reel		

<sup>1.</sup> Pulse Test: Pulse Width  $\leq~300\mu s,~Duty~Cycle \leq 2.0\%.$ 

### **Typical Electrical Characteristics**

#### BS170 / MMBF170

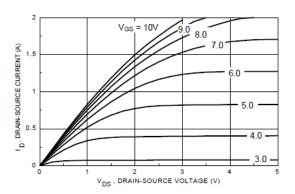


Figure 1. On-Region Characteristics.

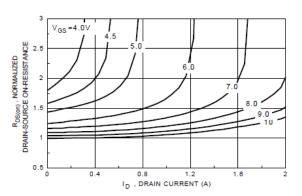


Figure 2. On-Resistance Variation with Gate Voltage and Drain Current.

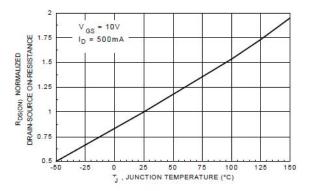


Figure 3. On-Resistance Variation with Temperature.

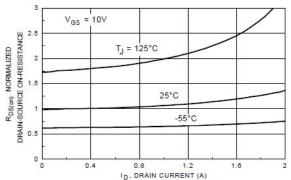


Figure 4. On-Resistance Variation with Drain Current and Temperature.

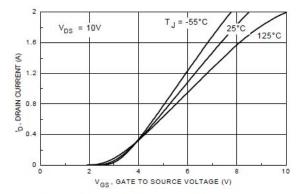


Figure 5. Transfer Characteristics.

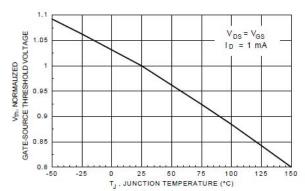


Figure 6. Gate Threshold Variation with Temperature.

### Typical Electrical Characteristics (continued)

#### BS170 / MMBF170

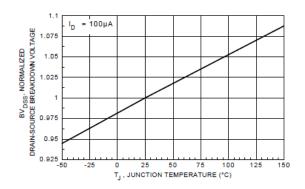


Figure 7. Breakdown Voltage Variation with Temperature.

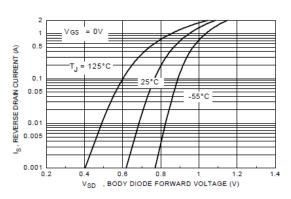


Figure 8. Body Diode Forward Voltage Variation with Current and Temperature.

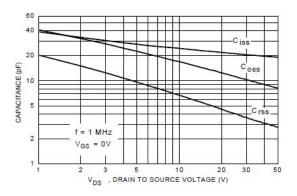


Figure 9. Capacitance Characteristics.

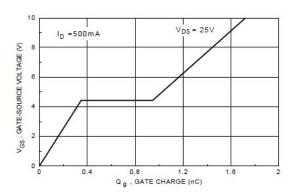


Figure 10. Gate Charge Characteristics.

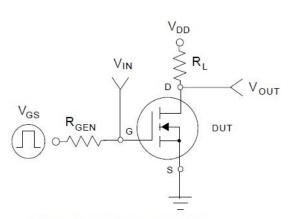


Figure 11. Switching Test Circuit.

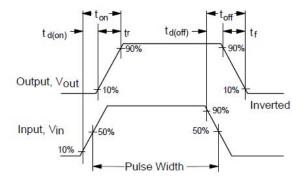
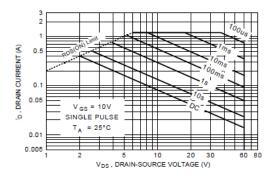


Figure 12. Switching Waveforms.

#### Typical Electrical Characteristics (continued)



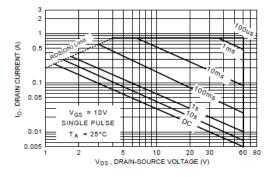


Figure 13. BS170 Maximum Safe Operating Area.

Figure 14. MMBF170 Maximum Safe Operating Area.

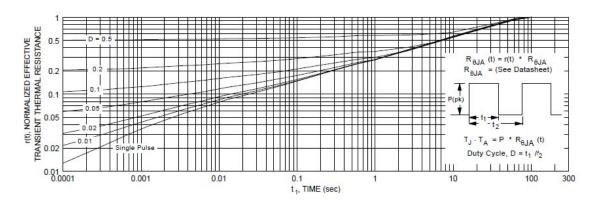


Figure 15. TO-92, BS170 Transient Thermal Response Curve.

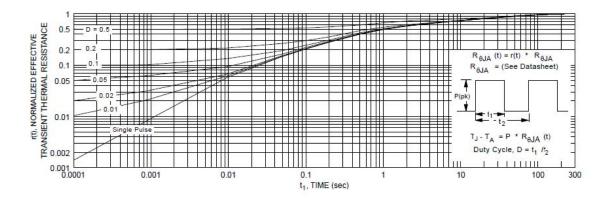
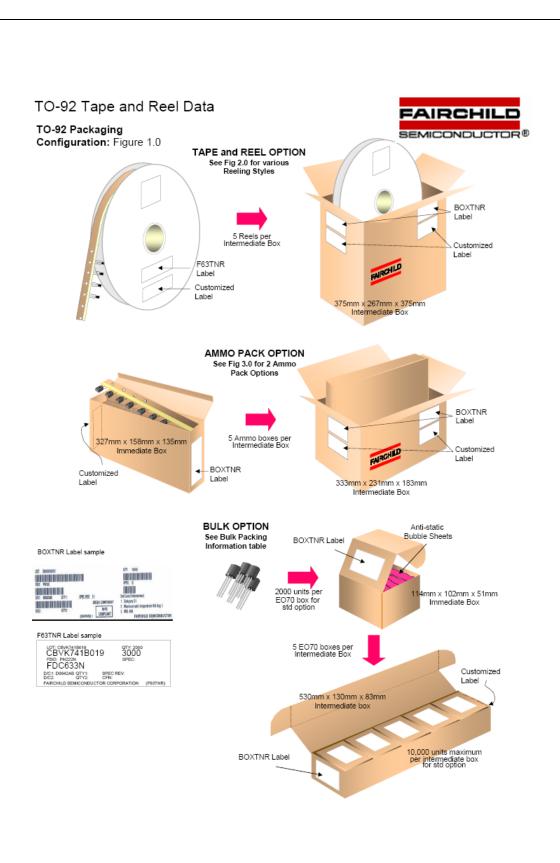


Figure 16. SOT-23, MMBF170 Transient Thermal Response Curve.



#### TO-92 Tape and Reel Data, continued



TO-92 Packing Information: Figure 2.0

TO-92 TNR/AMMO PACKING INFORMATION TABLE

Packing	Style	Quantity	EOL code
Reel	Α	2,000	D26Z
	В	2,000	D11Z
	С	2,000	D28Z
	D	2,000	D10Z
	E	2,000	D27Z
	F	2,000	D81Z
	G	2,000	D29Z
	Н	2,000	D89Z
Ammo	М	2,000	D74Z
	P	2,000	D75Z

Unit weight = 0.22 gm
Reel weight with components = 1.04 kg
Ammo weight with components = 1.02 kg
Max quantity per intermediate box = 10,000 units

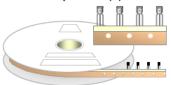
TO-92 BULK PACKING INFORMATION TABLE

EOL CODE /FLOW OPTION	DESCRIPTION	LEADCLIP DIMENSION	MINIMUM ORDER QTY	LEADFORM OULTINE
NO EOL CODE	STRAIGHT LEADS	NO LEAD CLIP	2.0K / BOX	-
J18Z	TO-18 OPTION STD	NO LEAD CLIP	2.0K / BOX	
J35Z	TO-18 OPTION REVERSE	NO LEAD CLIP	2.0K / BOX	
J05Z	TO-5 OPTION STD	NO LEAD CLIP	1.5K / BOX	
J60Z	TO-5 OPTION REVERSE	NO LEAD CLIP	1.5K / BOX	
J61Z	IN LINE 0.200 SPACING	NO LEAD CLIP	1.5K / BOX	

#### TO-92 Tape and Reel Data, continued

TO-92 Reeling Style Configuration: Figure 3.0

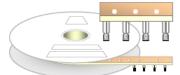
#### Machine Option "A" (H)



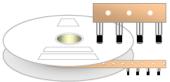
Style "A", D26Z



Style "B", D11Z



Style "C", D28Z



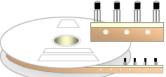
Style "D", D10Z

## TO-92 Radial Ammo Packaging Configuration: Figure 4.0

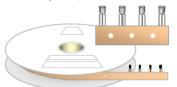




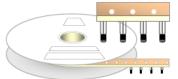
Machine Option "E" (J)



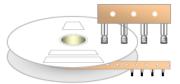
Style "E", D27Z



Style "F", D81Z



Style "G", D29Z



Style "H", D89Z

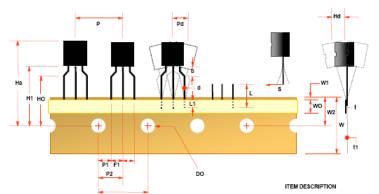


FIRST WIRE OFF IS COLLECTOR ADHESIVE TAPE IS ON BOTTOM SIDE FLAT OF TRANSISTOR IS ON TOP

#### TO-92 Tape and Reel Data, continued

TO-92 Tape and Reel Taping
Dimension Configuration: Figure 5.0





User Direction of Feed

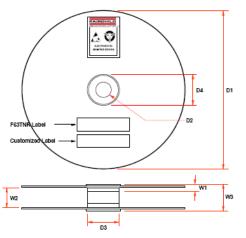
0.098 (max) Base of Package to Lead Bend Component Height Lead Clinch Height 0.928 (+/- 0.025) но 0.630 (+/- 0.020) Component Base Height 0.748 (+/- 0.020) 0.040 (max) 0.031 (max) Component Alignment ( side/side ) Pd Hd Component Alignment ( front/back ) Component Pitch Feed Hole Pitch 0.500 (+/- 0.020) РО 0.500 (+/- 0.008) Hole Center to Component Center P2 0.247 (+/- 0.007) 0.104 (+/- 0.010) F1/F2 Lead Spread 0.018 (+0.002, -0.003) Cut Lead Length 0.429 (max) 0.209 (+0.051, -0.052) L1 Taped Lead Length Taped Lead Thickness 0.032 (+/- 0.006) Carrier Tape Thickness tι 0.021 (+/- 0.006) Carrier Tape Width 0.708 (+0.020, -0.019) Hold - down Tape Width wo 0.236 (+/- 0.012) 0.035 (max) Hold - down Tape position 0.360 (+/- 0.025) 0.157 (+0.008, -0.007) DO Sprocket Hole Diamete

SYMBOL

DIMENSION

0.004 (max)

TO-92 Reel Configuration: Figure 6.0



ITEM DESCRIPTION	SYMBOL	MINIMUM	MAXIMUM	
Reel Dlameter	D1	13.975	14.025	
Arbor Hole Diameter (Standard)	D2	1.160	1.200	
(Small Hole)	D2	0.650	0.700	
Core Diameter	D3	3.100	3.300	
Hub Recess Inner Dlameter	D4	2.700	3.100	
Hub Recess Depth	W1	0.370	0.570	
Flange to Flange Inner Width	W2	1.630	1.690	
Hub to Hub Center Width	W3		2.090	

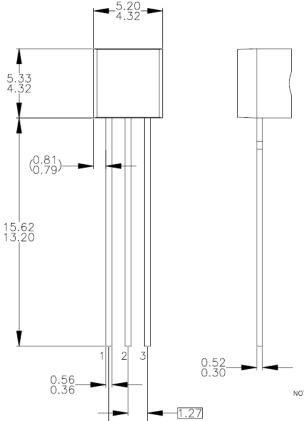
Note: All dimensions are inches

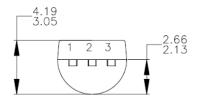
Lead Spring Out

Note : All dimensions are in inches

### **Mechanical Dimensions (TO-92)**

### **TO-92**





2.54

NOTES: UNLESS OTHERWISE SPECIFIED

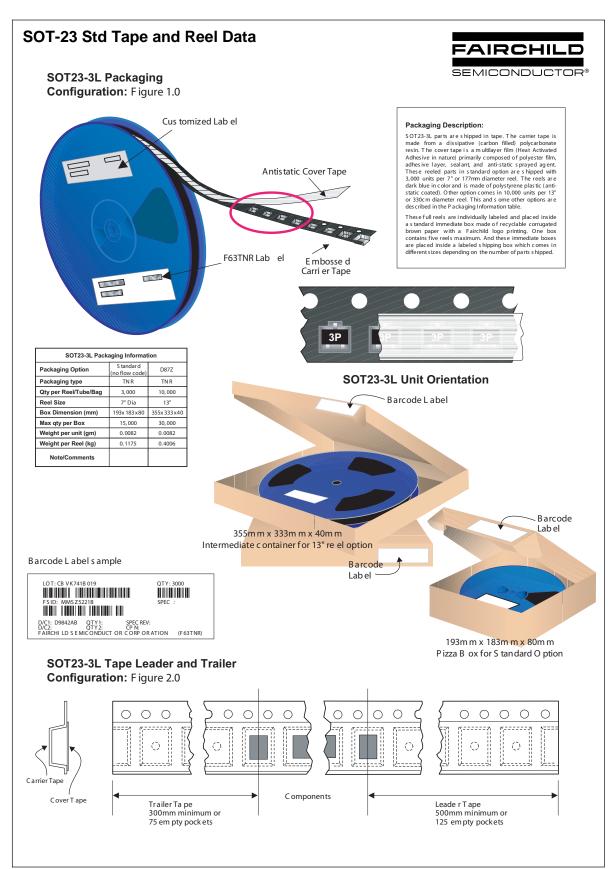
- DRAWING WITH REFERENCE TO JEDEC TO-92 RECOMMENDATIONS. ALL DIMENSIONS ARE IN MILLIMETERS. DRAWING CONFORMS TO ASME Y14.5M-1994. TO-92 (92,94,96,97,98) PIN CONFIGURATION:

z		92			94			96			97			98	
<u>a</u>	Р	F	М	Р	F	М	Р	F	М	Р	F	М	Р	F	М
1	Ε	S	S	Ε	S	S	В	D	G	С	G	D	С	G	D
2	В	D	G	С	G	D	Ε	S	S	В	D	G	Ε	S	S
3	С	G	D	В	D	G	С	G	D	Ε	S	S	В	D	G

LEGEND: P - BIPOLAR F - JFET M - DMOS E - EMITTER B - BASE C - COLLECTOR D - DRAIN S - SOURCE G - GATE

- FOR PACKAGE 92, 94, 96, 97 AND 98: PIN CONFIGURATION DRAIN "O" AND SOURCE "S" ARE INTERCHANGEAGLE AT JFET "F" OPTION. DRAWING FILENAME: MKT-ZAO3DREV3. E)

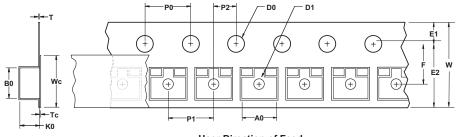
**Dimensions in Millimeters** 





#### **SOT23-3L Embossed Carrier Tape**

Configuration: Figure 3.0



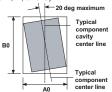
User [	Direction of Feed	

	Dimensions are in millimeter													
Pkg type	Α0	В0	w	D0	D1	E1	E2	F	P1	P0	K0	т	Wc	Тс
<b>SOT-23</b> (8mm)	3.15 +/-0.10	2.77 +/-0.10	8.0 +/-0.3	1.55 +/-0.05	1.125 +/-0.125	1.75 +/-0.10	6.25 min	3.50 +/-0.05	4.0 +/-0.1	4.0 +/-0.1	1.30 +/-0.10	0.228 +/-0.013	5.2 +/-0.3	0.06 +/-0.02

Notes: A0, B0, and K0 dimensions are determined with respect to the EIA/Jedec RS-481 rotational and lateral movement requirements (see sketches A, B, and C).



Sketch A (Side or Front Sectional View)
Component Rotation

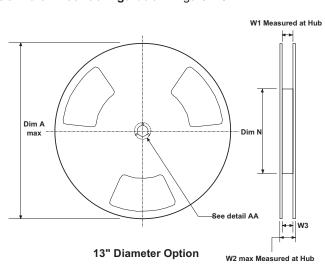


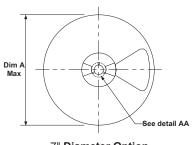
Sketch B (Top View)
Component Rotation



Sketch C (Top View)
Component lateral movement

#### SOT23-3L Reel Configuration: Figure 4.0





7" Diameter Option

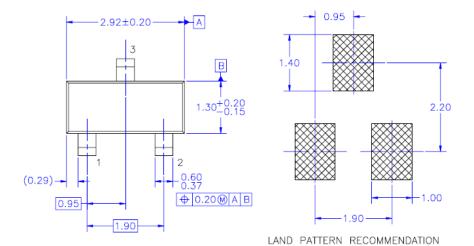
B Min

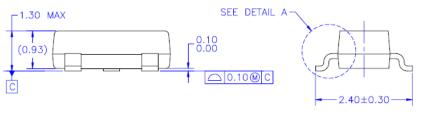
Dim C

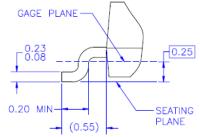
								DETAIL AA	ı	
	Dimensions are in inches and millimeters									
Tape Size	Reel Option	Dim A	Dim B	Dim C	Dim D	Dim N	Dim W1	Dim W2	Dim W3 (LSL-USL)	
8mm	7" Dia	7.00 177.8	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	2.165 55	0.331 +0.059/-0.000 8.4 +1.5/0	0.567 14.4	0.311 - 0.429 7.9 - 10. 9	
8mm	13" Dia	13.00 330	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	4.00 100	0.331 +0.059/-0.000 8.4 +1.5/0	0.567 14.4	0.311 - 0.429 7.9 - 10.9	

## **Mechanical Dimensions (SOT-23)**

## **SOT-23**







DETAIL A

- NOTES: UNLESS OTHERWISE SPECIFIED
  - REFERENCE JEDEC REGISTRATION TO-236, VARIATION AB, ISSUE H.
    ALL DIMENSIONS ARE IN MILLIMETERS.
    DIMENSIONS ARE INCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR EXTRUSIONS.
    DIMENSIONING AND TOLERANCING PER ASME Y14.5M 1994.
    DRAWING FILE NAME: MAO3DREV9

Dimensions in Millimeters



The Power Franchise®

uwer

franchise

TinyBoost™

TinvBuck™

TinyCalc™

TinyLogic<sup>®</sup>

TINYOPTO™

TinyPower™

TinyPWM™

TinyWire™

TriFault Detect™

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CROSSVOLT™ GTO™ CTL™ IntelliMAX™ Current Transfer Logic™ ISOPLANAR™ DEUXPEED® MegaBuck™

Dual Cool™ MIČROCOUPLER™ EcoSPARK® MicroFET™ EfficientMax™ MicroPak™

® MicroPak2™ MillerDrive™ Fairchild® MotionMax™ Fairchild Semiconductor® Motion-SPM™ FACT Quiet Series™ OptoHiT™ FACT OPTOLOGIC® FAST® OPTOPLANAR®

FETBench™ FlashWriter®\* PDP SPM™ FPS™ Power-SPM™ F-PFS™

PowerTrench® PowerXS™

Programmable Active Droop™

QS™ Quiet Series™ RapidConfigure™

Saving our world, 1mW/W/kW at a time™

SignalWise™ SmartMax™ SMART START™ SPM® STEALTH™ SuperFET™ . SuperSOT™-3 SuperSOT™-6 SuperSOT™-8 SupreMOS™ SyncFET™ Sync-Lock™

GENERAL

TRUECURRENT™\* μSerDes™ UHC Ultra FRFET™ UniFET™ VCX™ VisualMax™ XS™

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- 2. A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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#### PRODUCT STATUS DEFINITIONS

#### Definition of Terms

remittion of Terms									
Product Status	Definition								
Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.								
First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.								
Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.								
Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.								
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